SUM110P06-07L

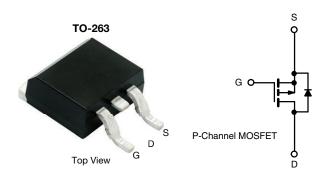


Vishay Siliconix

P-Channel 60 V (D-S) 175 °C MOSFET

FEATURES

PRODUCT SUMMARY				
V _{DS} (V)	V _{DS} (V) R _{DS(on)} (Ω)			
-60	0.0069 at V _{GS} = -10 V	-110		
	0.0088 at V _{GS} = -4.5 V	-110		



Ordering Information:

SUM110P06-07L-E3 (Lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted) PARAMETER SYMBOL UNIT LIMIT Drain-Source Voltage -60 V_{DS} ٧ Gate-Source Voltage ± 20 V_{GS} T_C = 25 °C -110 Continuous Drain Current ^d I_D $(T_{.1} = 175 \ ^{\circ}C)$ $T_C = 125 \circ C$ -95 А Pulsed Drain Current -240 I_{DM} Avalanche Current -75 I_{AS} L = 0.1 mHSingle Pulse Avalanche Energy ^a 281 mJ E_{AS} T_C = 25 °C ° 375 Power Dissipation W P_D $T_A = 25 \circ C^b$ 3.75 Operating Junction and Storage Temperature Range T_J, T_{stg} -55 to +175 °C

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	UNIT	
Junction-to-Ambient	PCB mount ^b	R _{thJA}	40	°C/W	
Junction-to-Case		R _{thJC}	0.4	0/11	

Notes

- a. Duty cycle ≤ 1 %.
- b. When mounted on 1" square PCB (FR4 material).
- c. See SOA curve for voltage derating.

d. Limited by package.

• TrenchFET[®] power MOSFET • Package with low thermal resistance

• Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



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SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = -250 \mu\text{A}$	-60	-	-	v
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 μA -1		-	-3	v
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	-	-	± 100	nA
Zero Gate Voltage Drain Current		$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	-1	
	I _{DSS}	V_{DS} = -60 V, V_{GS} = 0 V, T_{J} = 125 °C	-	-	-50	μA
		V_{DS} = -60 V, V_{GS} = 0 V, T_{J} = 175 °C	-	-	-250	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = -5 V, V_{GS} = -10 V$	-120	-	-	А
		V _{GS} = -10 V, I _D = -30 A	-	0.0055	0.0069	
Drain Source On State Resistance a	Б	V_{GS} = -10 V, I_D = -30 A, T_J = 125 °C	-	-	0.0115	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V_{GS} = -10 V, I_D = -30 A, T_J = 175 °C	-	-	0.0138	Ω
		$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -20 \text{ A}$	-	0.0070	0.0088	İ
Forward Transconductance a	9 _{fs}	V _{DS} = -15 V, I _D = -50 A	20	-	-	S
Dynamic ^b						
Input Capacitance	C _{iss}		-	11 400	-	pF
Output Capacitance	Coss	$V_{GS} = 0 V, V_{DS} = -25 V, f = 1 MHz$	-	1200	-	
Reverse Transfer Capacitance	C _{rss}		-	900	-	
Total Gate Charge ^c	Qg		-	230	345	nC
Gate-Source Charge ^c	Q _{gs}	V_{DS} = -30 V, V_{GS} = -10 V, I_D = -110 A	-	50	-	
Gate-Drain Charge ^c	Q _{gd}		-	60	-	
Gate Resistance	Rg	f = 1 MHz	-	3	-	Ω
Turn-On Delay Time ^c	t _{d(on)}		-	20	30	
Rise Time ^c	t _r	$V_{DD} = -30 \text{ V}, \text{ R}_{\text{L}} = 0.27 \Omega$	-	25	40	ns
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong -110$ A, $V_{GEN} = -10$ V, $R_g = 1$ Ω	-	110	200	
Fall Time ^c	t _f		-	50	100	
Drain-Source Body Diode Character	istics (T _C = 25	s °C b)				
Continuous Current	I _S		-	-	-110	A
Pulsed Current	I _{SM}		-	-	-240	А
Forward Voltage ^a	V _{SD}	I _F = -85 A, V _{GS} = 0 V	-	-1	-1.5	V
Reverse Recovery Time	t _{rr}		-	91	137	ns
Peak Reverse Recovery Charge	I _{RM(REC)}	I _F = -85 A, dl/dt = 100 A/μs	-	-6	-9	А
Reverse Recovery Charge	Q _{rr}		-	0.21	0.44	μC

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

4 V

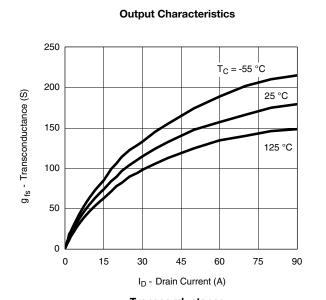
3 V

10

8

6 V_{DS} - Drain-to-Source Voltage (V)

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



4

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V_{GS} = 10 V thru 5 V

ISHAY

200

160

120

80

40

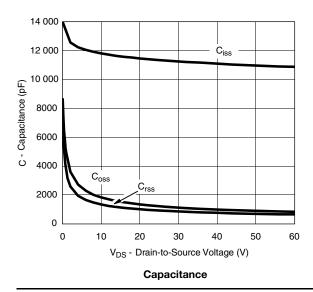
0

0

2

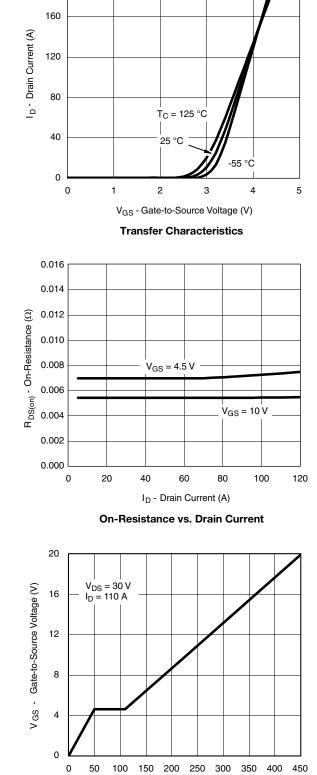
I_D - Drain Current (A)







200



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Total Gate Charge (nC)

Gate Charge

Qq

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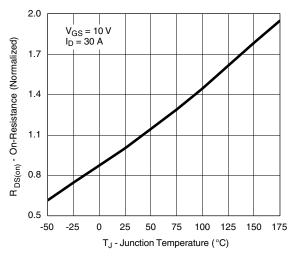
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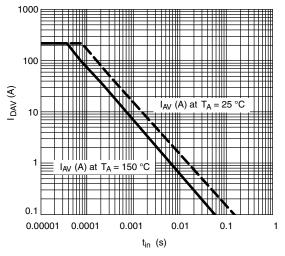
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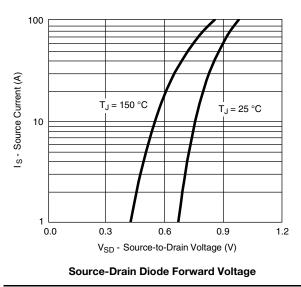
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

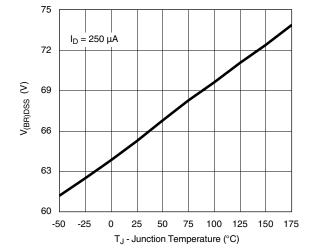


On-Resistance vs. Junction Temperature

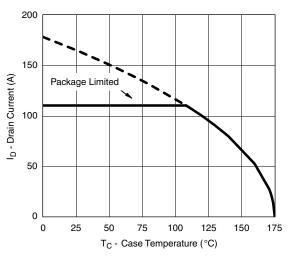




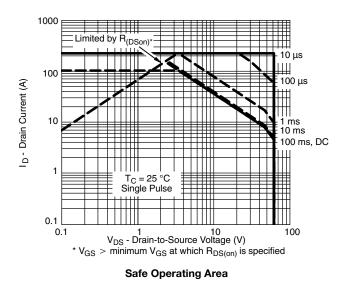




Drain Source Breakdown vs. Junction Temperature



Maximum Avalanche and Drain Current vs. Case Temperature



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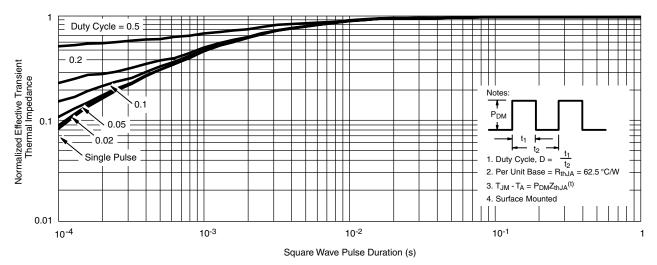
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?72439.



Vishay Siliconix

TO-263 (D²PAK): 3-LEAD









DETAIL A (ROTATED 90°)



		INC	HES	MILLIMETERS			
DIM.		MIN.	MAX.	MIN.	MAX.		
A		0.160	0.190	4.064	4.826		
	b	0.020	0.039	0.508	0.990		
	b1	0.020	0.035	0.508	0.889		
b2		0.045	0.055	1.143	1.397		
с*	Thin lead	0.013	0.018	0.330	0.457		
	Thick lead	0.023	0.028	0.584	0.711		
<u>1</u>	Thin lead	0.013	0.017	0.330	0.431		
c1	Thick lead	0.023	0.027	0.584	0.685		
	c2	0.045	0.055	1.143	1.397		
	D	0.340	0.380	8.636	9.652		
D1		0.220	0.240	5.588	6.096		
D2		0.038	0.042	0.965	1.067		
D3		0.045	0.055	1.143	1.397		
D4		0.044	0.052	1.118	1.321		
	E	0.380	0.410	9.652	10.414		
	E1	0.245	-	6.223	-		
E2		0.355	0.375	9.017	9.525		
	E3	0.072	0.078	1.829	1.981		
	е	0.100	0.100 BSC 2.54 BSC		BSC		
	К	0.045	0.055	1.143	1.397		
	L	0.575	0.625	14.605	15.875		
	L1	0.090	0.110	2.286	2.794		
L2		0.040	0.055	1.016	1.397		
	L3	0.050	0.070	1.270	1.778		
	L4	0.010 BSC		0.254 BSC			
	M - 0.002 - 0		0.050				
ECN: T13-0707-Rev. K, 30-Sep-13 DWG: 5843							

Notes

- 1. Plane B includes maximum features of heat sink tab and plastic. 2. No more than 25 % of L1 can fall above seating plane by
- max. 8 mils.3. Pin-to-pin coplanarity max. 4 mils.
- 4. *: Thin lead is for SUB, SYB.
 - Thick lead is for SUM, SYM, SQM.
- 5. Use inches as the primary measurement.

This feature is for thick lead.

Revison: 30-Sep-13



RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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